1. Record Nr. UNINA9910877721803321

Titolo	Lead-free electronics / / edited by Sanka Ganesan, Michael Pecht
Pubbl/distr/stampa	Hoboken, N.J., : Wiley-Interscience, c2006
ISBN	1-280-34963-8 9786610349630 0-470-00780-X 0-470-00779-6
Descrizione fisica	1 online resource (796 p.)
Altri autori (Persone)	GanesanSanka PechtMichael
Disciplina	621.3815
Soggetti	Electronic apparatus and appliances Lead-free electronics manufacturing processes
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Lead-free Electronics; Contents; Preface; Editors; Contributors; Acknowledgments; Chapter 1 Lead-free Electronics: Overview; 1.1 What Is Lead-free?; 1.2 Why Lead-free?; 1.2.1 Legislation; 1.2.2 Market differentiation; 1.2.3 Environmental stewardship; 1.3 Who Are the First Consumers for Lead-free Products?; 1.3.1 Affluent societies; 1.3.2 Social/cultural motivation; 1.3.3 Consumer response to lead-free electronics; 1.4 Are There Any Technical Barriers to Lead-free Electronics?; 1.4.1 Technical issues; 1.4.2 Reliability concerns; 1.5 How Will We Migrate to Lead-free Electronics? 1.5.1 Potential mismatches: obsolescence and compatibility1.5.2 Supply chain issues; 1.6 When Will Lead-free Products Be Widely Available?; 1.6.1 Recycling and material recovery systems; 1.7 summary; 1.8 References; Chapter 2 Lead-free Legislations, Exemptions, and Compliance; 2.1 Overview of the Lead-free Legislation; 2.1.1 WEEE Directive; 2.1.2 RoHS Directive; 2.1.3 Electronic Waste Recycling Act in California; 2.1.4 Hazardous material ban in China; 2.2 Exemptions; 2.2.1 Lead in glass of cathode ray tubes, electronic components and fluorescent tubes 2.2.2 Lead in high melting temperature type solders2.2.3 Lead in

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Sommario/riassunto

Lead-free Electronics provides guidance on the design and use of lead-free electronics as well as technical and legislative perspectives. All the complex challenges confronting the elec-tronics industry are skillfully addressed:* Complying with state legislation* Implementing the transition to lead-free electronics, including anticipating associated costs and potential supply chain issues* Understanding intellectual property issues in lead-free alloys and their applications, including licensing and infringement* Implementing cost effective manufacturing and testing* Reducin